

SCOPE OF CLAIMS

1. A paste composition containing an inorganic filler, a resin and a solvent, wherein the paste composition is characterized in that it contains one or more solvents of which boiling point is 160°C or higher and an inorganic filler of which mean particle diameter is 5 µm or smaller, and the total content of the solvent being 25 wt% or less based on the total amount of the paste composition.
- 10 2. A paste composition according to claim 1, wherein the inorganic filler is at least one selected from the group consisting of a barium titanate type, a barium zirconate titanate type, a strontium titanate type, a calcium titanate type, a bismuth titanate type, a magnesium titanate type, a barium neodymium titanate type, a barium tin titanate type, a barium magnesium niobate type, a barium magnesium tantalate type, a lead titanate type, a lead zirconate type, a lead zirconate titanate type, a lead niobate type, a lead magnesium niobate type, a lead nickel niobate type, a lead tungstate type, a calcium tungstate type, a lead magnesium tungstate type, and a titanium dioxide type.
- 20 3. A paste composition according to claim 1, wherein the inorganic filler contains inorganic fillers of at least two kinds of mean particle diameter, and the greatest mean particle diameter of said mean particle diameters is 0.1-5 µm and is 3 times or more

to the minimum mean particle diameter.

4. A paste composition according to claim 1, which contains at least one kind of solvent having an ester structure.

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5. A paste composition according to claim 1, which contains at least one kind of solvent having a lactone structure.

6. A paste composition according to claim 1, wherein the resin
10 contains a thermosetting resin.

7. A paste composition according to claim 1, wherein the thermosetting resin is an epoxy resin.

15 8. A paste composition according to claim 1, which contains a compound having a phosphoric ester skeleton.

9. A dielectric composition obtainable by removing solvent from and solidifying the paste composition described in anyone of claims
20 1 to 8, wherein the content of the inorganic filler is 85 to 99 wt% based on the total amount of the solid component contained in the dielectric composition, and a porosity is less than 30 volume%.

10. A high dielectric constant composition according to claim 9,
25 wherein it has a film configuration having a film thickness of 0.5

μm or thicker and 20 μm or thinner.

11. A dielectric composition containing an inorganic filler and a resin characterized in that the inorganic filler includes inorganic fillers of at least two kinds of mean particle diameter, and the greatest mean particle diameter of said mean particle diameters is 0.1-5 μm and is 3 times or more to the minimum mean particle diameter.
- 10 12. A dielectric composition according to claim 11, wherein the inorganic filler is at least one selected from the group consisting of a titanium dioxide type, a barium titanate type, a barium zirconate titanate type, a strontium titanate type, a calcium titanate type, a bismuth titanate type, a magnesium titanate type, a barium neodymium titanate type, a barium tin titanate type, a barium magnesium niobate type, a barium magnesium tantalate type, a lead titanate type, a lead zirconate type, a lead zirconate titanate type, a lead niobate type, a lead magnesium niobate type, a lead nickel niobate type, a lead tungstate type, a calcium tungstate type and a lead magnesium tungstate type.
- 25 13. A dielectric composition according to claim 11, wherein, Vf, a volume ratio of the total volume of the inorganic filler to the total volume of the inorganic filler plus the total volume of the solid resin is 50% or more and 95% or less.

14. A dielectric composition according to claim 11, wherein said resin contains a thermosetting resin.

5 15. A dielectric composition according to claim 11, wherein said resin is an epoxy resin.

16. A dielectric composition according to claim 11, which contains a compound having a phosphoric ester skeleton.

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17. A capacitor using the paste composition or the dielectric composition of claim 1 or 11.

18. An optical wiring using the paste composition or the
15 dielectric composition of claim 1 or 11.